

METHOD FOR MANUFACTURING ENCAPSULATED ELECTRONIC COMPONENTS,
PARTICULARLY INTEGRATED CIRCUITS

ABSTRACT

A method for manufacturing encapsulated electronic components, particularly integrated circuits, includes the steps of: a) attaching electronic components on a first side of a lead frame and electrically connecting the electronic components to the lead frame; b) using a mould to encapsulate the electronic components with an encapsulating material on just a first side of the lead frame, while a second side of the lead frame is substantially completely shielded with the aid of an adhesive film; and c) removing the adhesive film and separating, along cutting lines, individual encapsulated electronic components. The bonding of the adhesive film to the second side to be shielded of the lead frame takes place between step a) and step b).